

WHAT IS CLAIMED IS:

1. A manufacturing method of a module card comprising steps of:
 providing a base board having a golden finger;
 mounting a chip on said base board for electrically connecting to said
 5 golden finger; and
 forming a packing layer on said chip for forming said module card.
2. A manufacturing method according to Claim 1 wherein said base
 board includes a first surface and a second surface for mounting a
 plurality of said chips on said first surface and said second surface.
- 10 3. A manufacturing method according to Claim 1 wherein said base
 board includes a plurality of package areas for packing a plurality of
 said module cards once.
4. A manufacturing method according to Claim 1 wherein said packing
 layer includes a material of epoxy mold compound.
- 15 5. A manufacturing method according to Claim 1 wherein said base
 board is a circuit board, and said circuit board is a printed circuit board.
6. A module card comprising:
 a base board;
 a chip mounting on a surface of said base board;
 20 a golden finger on said board and electrically connecting to said chip;
 and
 a packing layer forming on said chip for covering said chip.
7. A module card according to Claim 6 wherein said packing layer
 includes a material of epoxy mold compound.
- 25 8. A module card according to Claim 6 wherein said surface of said base
 board includes a first surface and a second surface for packing a
 plurality of said chips.

Dec 04 01 03:26p

Lin Yun Cheng, Esq.

408-896-8625

P. 14

9. A module card according to Claim 6 wherein said module card is double sided.

10. A module card according to Claim 6 wherein said base board is a circuit board, and said circuit board is a printed circuit board.

5

1004021-24021001